



2829

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Michitaka Urushima

Serial No.: 09/839,298

Group Art Unit: 2829

Filed: April 23, 2001

Examiner: Geyer, Scott B.

For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE
SAMEHonorable Commissioner of Patents
Washington, D.C. 20231#6/Amendment
8/24/02
C. ParisAMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated May 9, 2002, please amend the above-
identified application as follows:

IN THE CLAIMS:

Please cancel claims 10-24 without prejudice or disclaimer.

Please amend claims 2, 5 and 7-9 as follows:

2. (Amended) the semiconductor device according to claim 1, further comprising:
an interposer bonded through thermocompression bonding.

5. (Amended) A semiconductor device comprising:
a semiconductor chip;
an adhesive layer formed on a surface of said semiconductor chip on which an
electrode is formed;

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